

BB02-EA :- 1.27mm x 2.54mm (0.05" x 0.1") SOCKET, DUAL ROW, STRAIGHT, THROUGH HOLE, 6 - 100 CONTACTS

SPECIFICATIONS

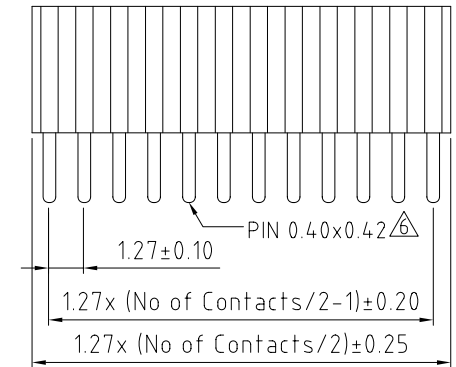
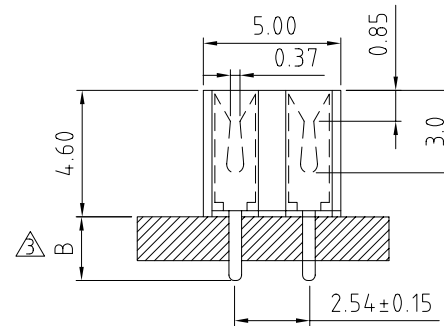
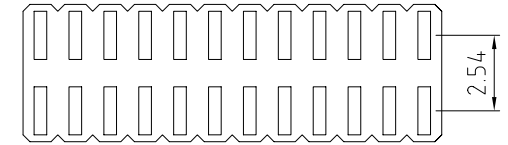
CURRENT RATING 1 AMP
 INSULATOR RESISTANCE 1000 MEGOHMS MIN.
 CONTACT RESISTANCE 20m ohms MAX.
 DIELECTRIC WITHSTANDING AC 300 V
 OPERATING TEMPERATURE -40°C TO +105°C
 CONTACT MATERIAL PHOSPHOR BRONZE
 INSULATOR MATERIAL POLYESTER, UL 94V-0
 STANDARD: NYLON 6T
 PLATING GOLD OR TIN OVER 30~50U" NICKEL
 SOLDERABILITY IR REFLOW: 260°C FOR 10 SEC
 WAVE: 230°C FOR 5-10 SEC
 MANNUAL SOLDER: 350°C FOR 3-5 SEC

PACKED IN TUBE OR TRAY.

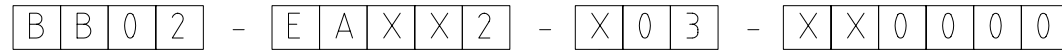
NOTES:

1. RECOMMANDED MATING PIN LENGTH: 2.5MM. Δ

MATES WITH :- BB02-DA
 BB02-DE
 BB02-DF
 BB02-DG



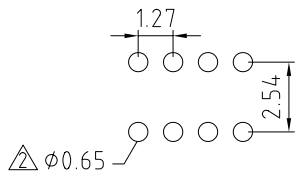
HOW TO ORDER



NO. OF CONTACTS
 06 TO 98
 100 Contacts= 00

CONTACT PLATING OPTIONS
 K = GOLD FLASH (STANDARD)
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 T = BRIGHT TIN
 M = MATT TIN

PIN LENGTH B Δ
 15 = 1.5 MM
 24 = 2.4 MM (STANDARD)
 30 = 3.0 MM
 TOL. ±0.20mm



RECOMMENDED PC BOARD HOLE LAYOUT
 (TOLERANCE: ±0.05)

REV.	DATE	BY	DESCRIPTION
10	28/05/03	NYW	RELEASE
11	22/02/05	NYW	DRAWING MODIFICATION
12	27/07/05	NYW	AMEND PCB LAYOUT
13	17/10/05	NYW	AMEND PCB LAYOUT
14	24/07/06	NYW	AMEND PIN LENGTH OPTION
15	13/09/07	NYW	DRAWING MODIFICATION
16	18/07/08	NYW	ADD NOTES 1
17	30/12/08	CHC	AMEND PIN SIZE, PLATING MODIFICATION, ADD MATT TIN PLATING
18	30/12/08	CHC	AMEND PIN SIZE, PLATING MODIFICATION

Scale:	5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material	SEE NOTE
Drawn:	CHC				
App'd:	XXXX	Title	SOCKET		NOT TO SCALE
Date:	30 DEC '08	Revision:	18	UNIT:	mm

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Type:	BB02-EA
BB02-EA	
Drawing Number:	
Sheet 1	of 1
Drawing	© E and O E